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Space product assurance - Design, selection, procurement and use of die form monolithic microwave integrated circuits (MMICs); English version EN 16602-60-12:2014

Contents

Page

Foreword 6

Introduction 7

1 Scope 8

2 Normative references 9

3 Terms, definitions and abbreviated terms 10

3.1 Terms from other standards 10

3.2 Terms specific to the present document 10

3.3 Abbreviated terms 12

4 General requirements 14

4.1 Overview 14

4.2 Flight model MMIC dies lots procurement 14

4.3 Minimum quality requirements 14

5 Selection 15

5.1 General 15

5.1.1 Overview 15

5.1.2 Requirements 15

5.2 Process selection 16

5.3 Models, and design tools 16

6 Responsibilities 17

7 MMIC design 18

7.1 Principles of MMIC design 18

7.1.1 Overview 18

7.1.2 General 18

7.1.3 Number of design iterations 18

7.1.4 Design trade-offs 19

7.2 Design tasks 19

7.2.1 Electrical design specification 19

7.2.2 Design variations 19

7.2.3 Parasitic effects....19
7.2.4 Transient simulation....20
7.2.5 Thermal analysis....20
7.2.6 Sensitivity to temperature, process variation and supply voltages....20
7.2.7 Design testability....21
7.2.8 Design stability analysis....21
7.2.9 Maximum rating and robustness....21
7.2.10 Layout optimization....22
7.2.11 DRC or ERC....22
7.3 Design reviews....23
7.3.1 General....23
7.3.2 MMIC architecture....23
7.3.3 Schematic....23
7.3.4 Simulation results....23
7.3.5 Sensitivity and stability analysis....24
7.3.6 Derating....24
7.3.7 Layout....24
7.3.8 Tests matrix....24
7.3.9 Assembly....24
7.3.10 Compliance matrix....25
7.3.11 MMIC detail specification....25
7.3.12 Development plan....25
7.3.13 Design documentation....25
7.3.14 MMIC summary design sheet....25
8 Application approval....26
8.1 General....26
8.2 Test flow and test procedures....26
9 Procurement and LAT specification....28
10 Procurement....29
10.1 General....29
10.1.1 Overview....29
10.1.2 Methodology....29
10.2 Wafer screening and WAT....29
10.2.1 General....29
10.2.2 Wafer screening and WAT flows....29
10.2.3 Wafer manufacturing and control....30

10.2.4 Wafer acceptance test 31
10.2.5 Packaging 32
10.2.6 Deliverables 32
10.3 Dies incoming testing 33
10.3.1 General 33
10.3.2 Assembly test 33
10.3.3 Visual inspection 34
10.3.4 Electrical characterization 34
10.4 User LAT procurement sequences 35
10.4.1 General 35
10.4.2 Sequence A: process, design and application validated 38
10.4.3 Sequence B: process validated and new design or new application 38
10.4.4 Sequence C: process, design and application not validated 39
10.4.5 Sequence D: application approval testing 40
10.4.6 Destructive physical analysis after user LAT 40
10.5 Failure criteria and lot failure 41
Annex A (normative) MMIC electrical design specification - DRD 42
Annex B (normative) Compliance matrix for custom MMIC design - DRD 43
Annex C (normative) Design package document - DRD 44
Annex D (normative) MMIC summary design sheet - DRD 46
Annex E (normative) MMIC procurement specification - DRD 47
Annex F (normative) MMIC lot acceptance specification for user LAT - DRD 48
Annex G (normative) MMIC visual inspection summary sheet - DRD 50
Annex H (informative) References 51
Bibliography 52

Figures

Figure 10-1: Wafer screening and WAT 30
Figure 10-2: Dies or die incoming testing 34
Figure 10-3: Acceptance flow for flight model die lots 35
Figure 10-4: User LAT flow 37

Tables

Table 6-1: Customer and supplier responsibilities for the “foundry” and “catalogue” modes 17
Table 8-1: CTA tests and procedures for testing in sequence D 27